



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	22-09-2020
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Representative Title	MDG MD CHAMPION
Authorized Representative *	MDG MD CHAMPION	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement		
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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>	

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24C32-FMN6TP	PHO7*24321TA	A	3068	22-09-2020
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	NiPdAu-Ag connections coating	

Package Designator	Size	Nbr of instances	Shape	
SON	NAC	8	Gull Wing	
Comment	Package : 07 SO 08 .15 JEDEC 0016023			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PH07*24321TA				6999999.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.321	mg	supplier	die	Silicon (Si)	7440-21-3		0.309	mg	962617	3863
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	3115	13
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	3115	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.010	mg	31153	125
Lead-frame	M-011 Other inorganic materials	17.694	mg	supplier	alloy	Copper (Cu)	7440-50-8		17.243	mg	974500	215538
				supplier	alloy	Iron (Fe)	7439-89-6		0.415	mg	23460	5189
				supplier	alloy	Zinc (Zn)	7440-66-6		0.021	mg	1200	265
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.015	mg	840	186
Lead-frame Coating	M-011 Other inorganic materials	0.078	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.071	mg	914840	890
				supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	29660	29
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	27750	27
				supplier	coating	Silver (Ag)	7440-22-4		0.002	mg	27750	27
Die Attach	M-011 Other inorganic materials	0.208	mg	supplier	glue or soft solder	Aluminium Oxide	1344-28-1		0.042	mg	200000	520
				supplier	glue or soft solder	Bismaleimide resin	Proprietary		0.042	mg	200000	520
				supplier	glue or soft solder	Boron nitride	10043-11-5		0.042	mg	200000	520
				supplier	glue or soft solder	Acrylic resin	Proprietary		0.042	mg	200000	520
				supplier	glue or soft solder	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.016	mg	75000	195
				supplier	glue or soft solder	High boiling methacrylate	Proprietary		0.005	mg	25000	65
				supplier	glue or soft solder	Additive	Proprietary		0.010	mg	50000	130
				supplier	glue or soft solder	Treated fumed silica	67762-90-7		0.005	mg	25000	65
Wires	M-011 Other inorganic materials	0.029	mg	supplier	glue or soft solder	Bis(.alpha.,.alpha.-Dimethylbenzyl) peroxide	80-43-3		0.005	mg	25000	65
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	365
Encapsulation	M-011 Other inorganic materials	61.669	mg	supplier	Moulding Compound	Epoxy Resin	Proprietary		4.612	mg	74793	57655
				supplier	Moulding Compound	Phenol Resin	Proprietary		3.075	mg	49862	38437
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		53.428	mg	866369	667850
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.307	mg	4986	3844
				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.246	mg	3989	3075
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	914840	9
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	29660	0
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	27750	0
				supplier	connections coating	Silver (Ag)	7440-22-4		0.000	mg	27750	0

